

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4425	(sphere microbump microball ball bump bga) with (interpos \$4) with (thru through hole via throughhole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/29 13:09
L2	1060	(chip semiconductor die ic (integrated adj circuit) microelectronic component) with 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/29 13:10
L3	712	(substrate carrier board pcb ) same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/29 13:10

8/ 29/ 08 1:11:18 PM

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